

Title (en)  
APPARATUS AND METHOD FOR CHEMICAL MECHANICAL POLISHING OF SUBSTRATES

Title (de)  
VERFAHREN UND VORRICHTUNG ZUM CHEMISCH-MECHANISCHEN POLIEREN VON SUBSTRATEN

Title (fr)  
DISPOSITIF ET PROCEDE DE POLISSAGE MECANO-CHIMIQUE DE SUBSTRATS

Publication  
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Application  
**EP 01962336 A 20010731**

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Abstract (en)  
[origin: WO0209906A1] A chemical mechanical polishing system having a wafer carrier assembly is provided. The wafer carrier assembly includes a wafer carrier support frame, (52) a wafer carrier head housing (56) rotatably mounted on the wafer carrier support frame, with a wafer carrier base including a bladder bellows (98) operatively connecting the wafer carrier base to the wafer carrier head housing. A retaining ring (96) is also provided, connected to a retaining ring bearing (142) that allows relative axial motion while constraining relative radial motion between the retaining ring and wafer carrier head housing, and a retaining ring bellows (144) to urge the retaining ring against a polishing member. A chamber formed by the bladder bellows, wafer carrier base and wafer carrier housing may be pressurized to load the wafer carrier base, and wafer, against a polishing member, independent of any frictional loads on the retaining ring.

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